

PAD
 KEEP OUT AREA

P.C.B LAYOUT MOUNTING PATTERN

MATERIALS:

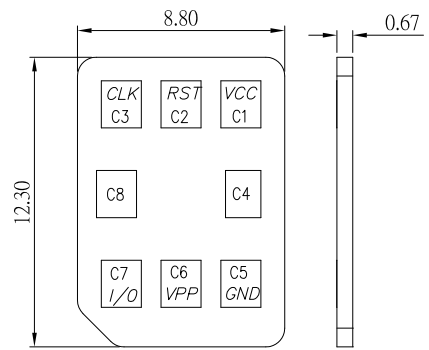
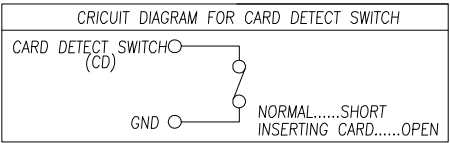
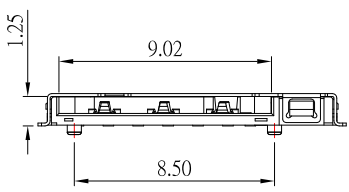
- HOUSING : HIGH TEMPERATURE THERMOPLASTIC
- TERMINAL : COPPER ALLOY
- SHELL : SUS

Finish:

- Finish: CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
- SHELL: NICKEL UNDER PLATED SURFACE LAYER

SPECIFICATION:

- RATING : 1.0A , 30V
- DIELECTRIC WITHSTANDING VOLTAGE : 500V AC
- INSULATION RESISTANCE : 1000MΩ MIN.
- CONTACT RESISTANCE : 50mΩ MAX.
- OPERATING TEMPERATURE : -40°C TO +85°C.



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

ITEM NO.	DESCRIPTION	DRAWN	DATE
8	更新圖面	Jack	031921
7	更新OPERATING TEMPERATURE	Jack	011521
6	更新圖面	Jack	121820
5	新增尺寸	Jack	120920
4	更新RATING	Jack	082420
3	更新圖面	Jack	052819
2	新增尺寸	Jack	052019
1	新增線路標示	Jack	051419

建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :

Up to 5	±0.2
Above 5 ~ 15	±0.3
Above 15 ~ 30	±0.4
Above 30 ~ 50	±0.5
Angle	±0.3

3RD. ANGEL'S

DRAWN BY: Jack Lu
 CHECKED BY: Jacky Chen
 APPROVED BY: Tony Kao

DATE	MAT'L	TITLE	CONNECTOR
03/19/21		MODLE	Nano SIM CARD SOCKET 6PIN 1.35H
03/19/21		DWG NO.	NSIM-510010632S-S304
03/19/21		PART NO.	NSIM-510010632S-S304

UNITS MM

SIZE
A4
VER
R8